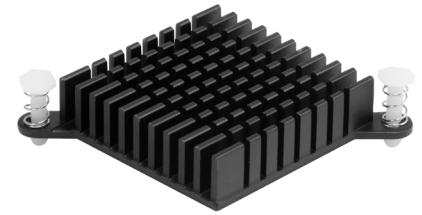


MODEL: HSB30-373710 | **DESCRIPTION:** HEAT SINK**FEATURES**

- BGA design
- low profile
- aluminum alloy

**MODEL**

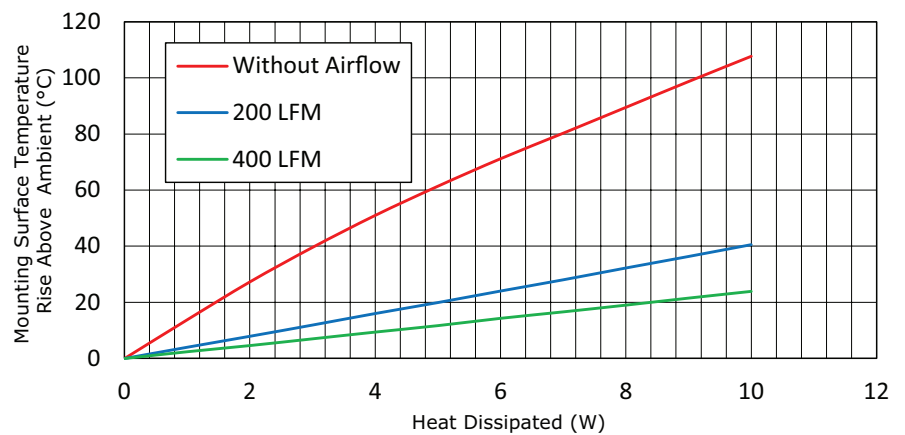
	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
HSB30-373710	11.63	13.8	4.0	2.4	6.45

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	13.8	4.0	2.4
2	27.3	7.9	4.6
3	39.6	11.9	7.0
4	51.0	16.0	9.4
5	61.4	19.9	11.7
6	71.2	24.0	14.3
7	80.3	28.0	16.6
8	89.5	32.2	19.0
9	98.7	36.3	21.5
10	107.7	40.5	23.9

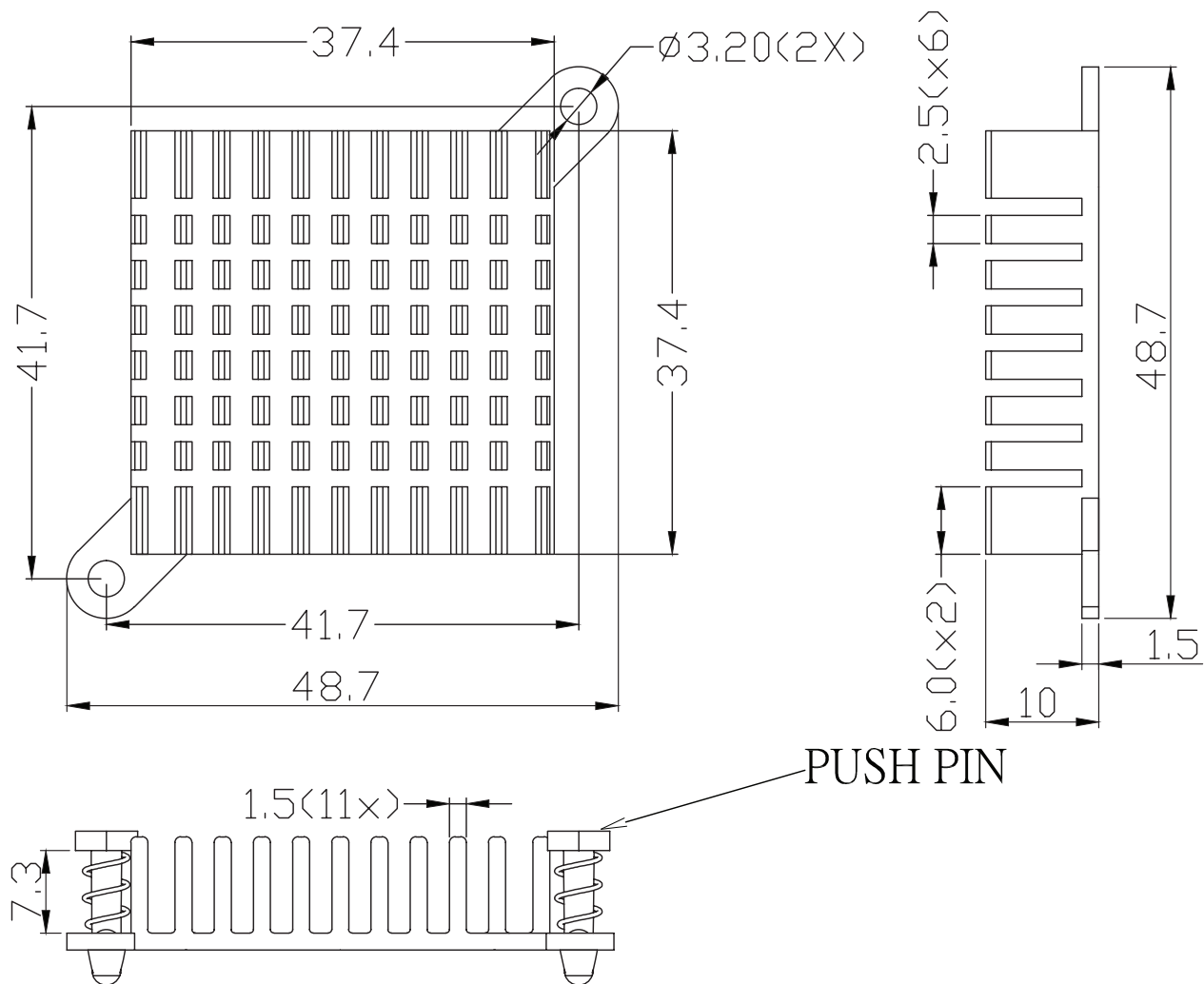
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ± 0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PUSH PIN	PA66
SPRING	spring steel, nickel plated
WEIGHT	20.8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/22/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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